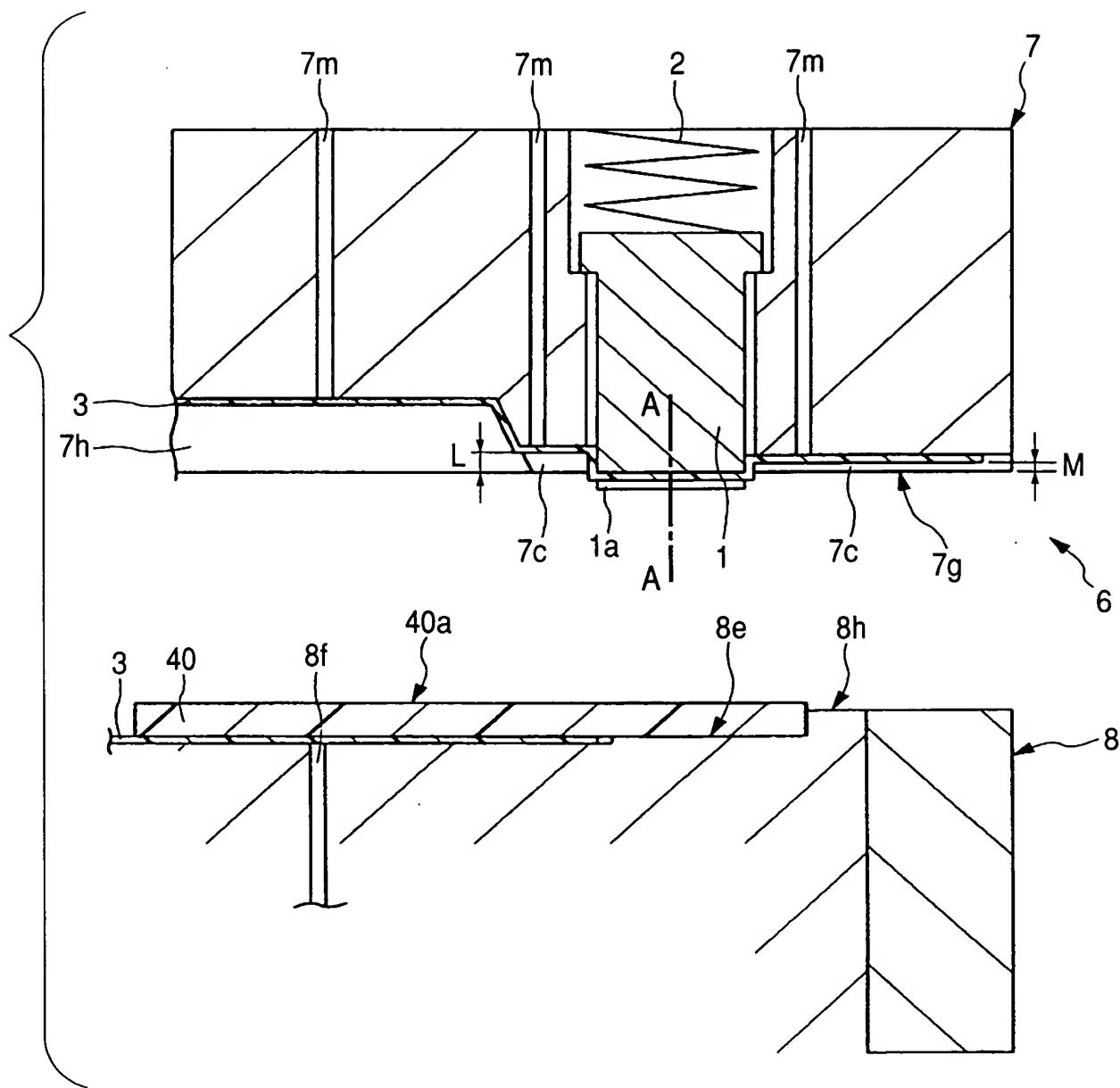


FIG. 1



1 : MOVABLE PIN
 1a : GROOVE
 2 : SPRING FOR DRIVING
 MOVABLE PIN (SPRING)
 3 : FILM
 6 : FORMING MOLD
 7 : UPPER MOLD (FIRST MOLD)

7c : AIR VENT
 7g,8h : MOLD SURFACE
 7h : COLLECTIVE CAVITY
 7m,8f : SUCTION HOLE
 8 : LOWER MOLD (SECOND MOLD)
 40 : MULTI-CAVITY BOARD (BOARD)

FIG. 2

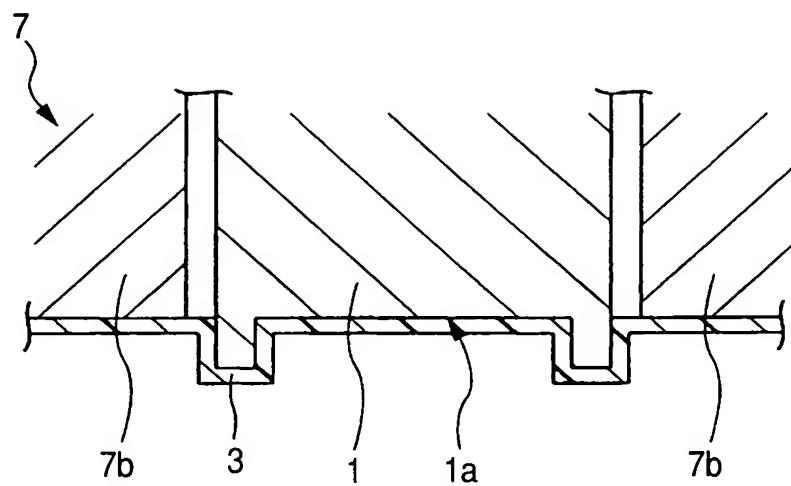
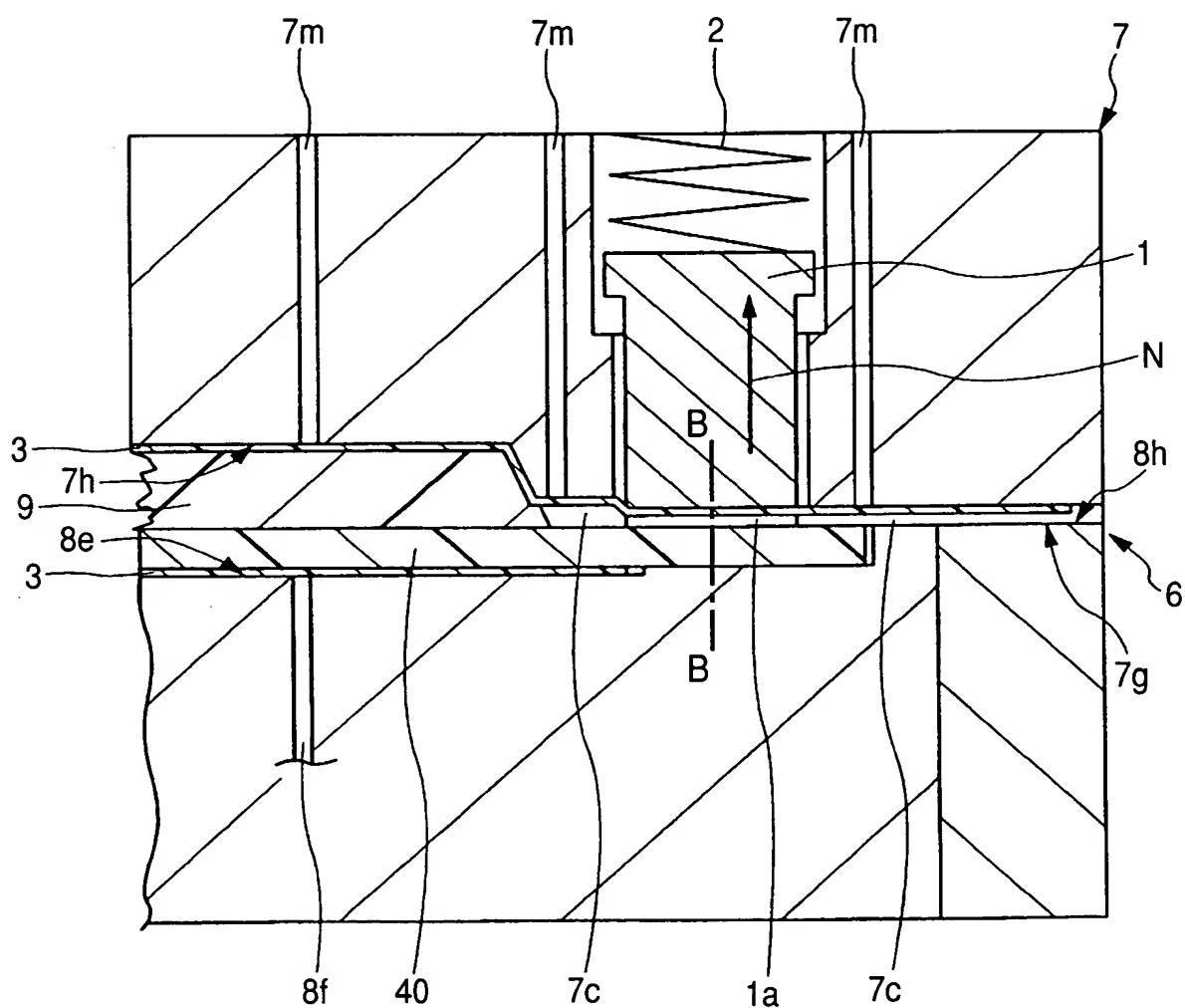


FIG. 3



9 : SEALING RESIN

FIG. 4

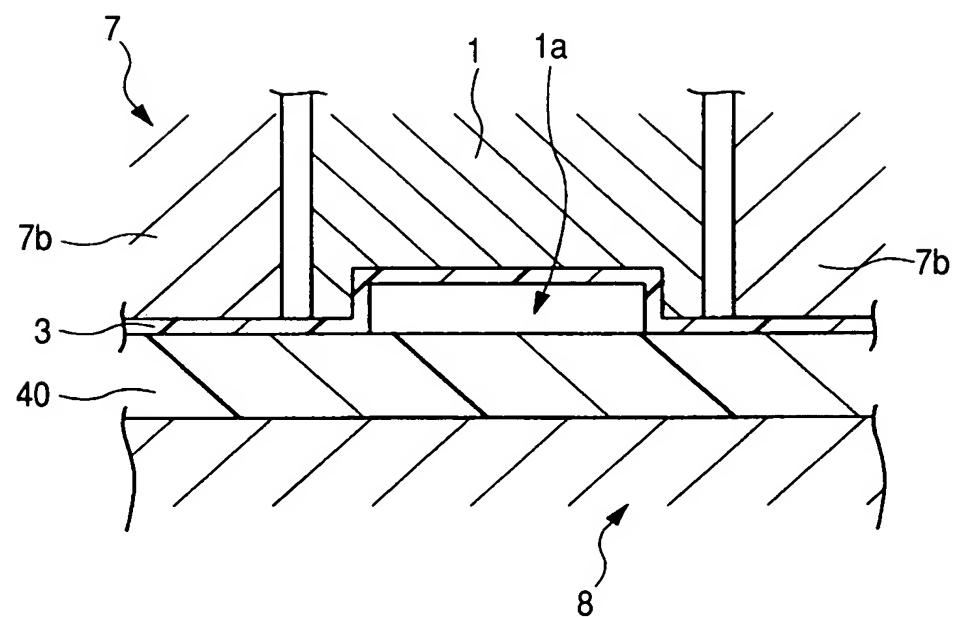
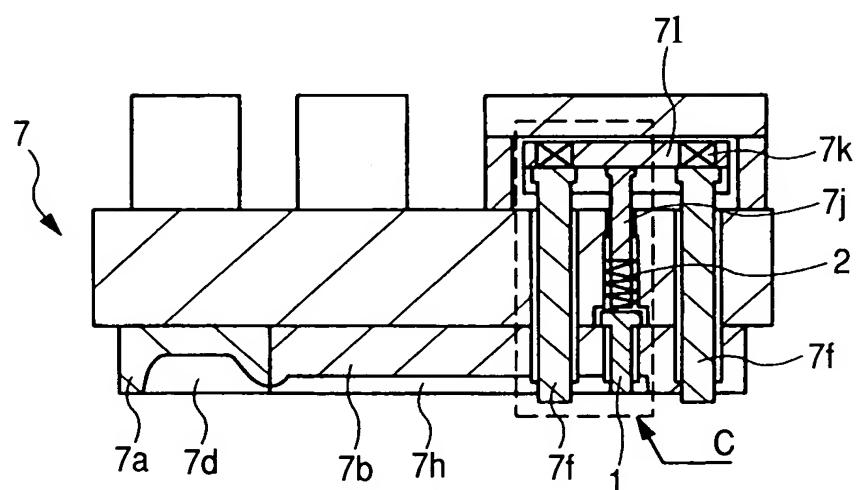


FIG. 5



7j : RAMMER FOR MOVABLE PIN (PUSHER ROD)

FIG. 6

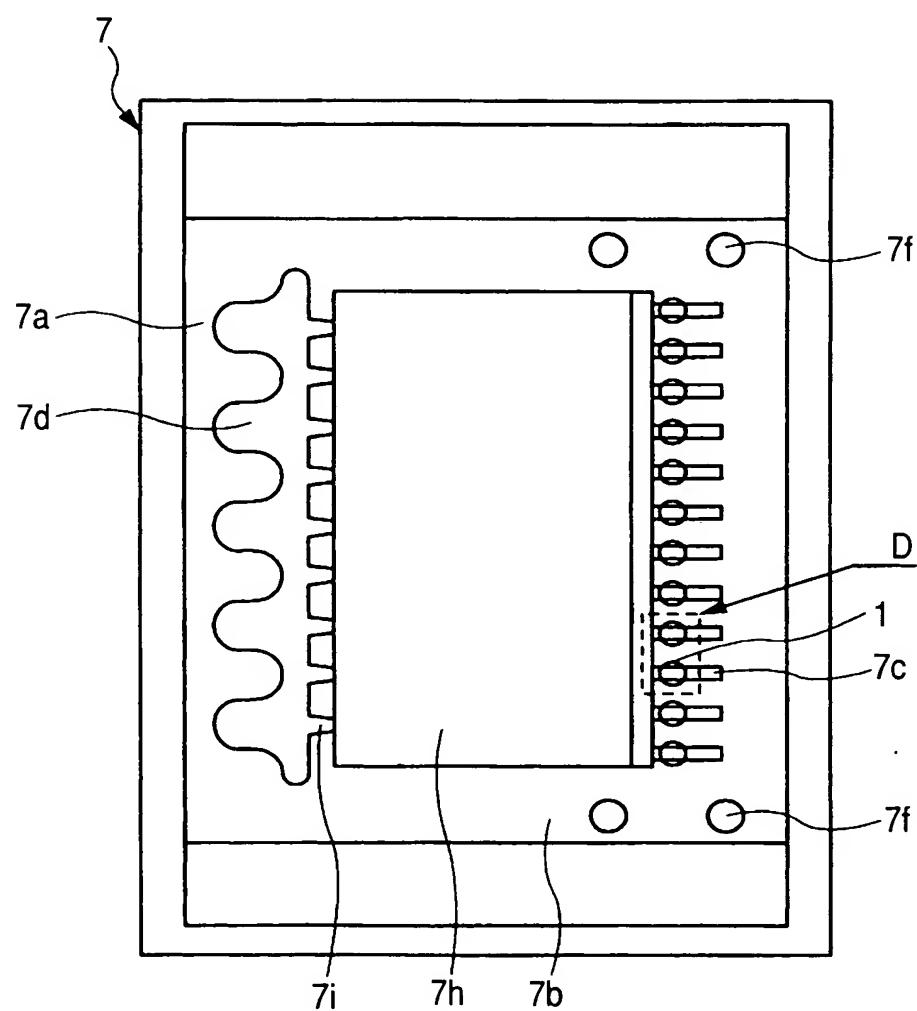


FIG. 7

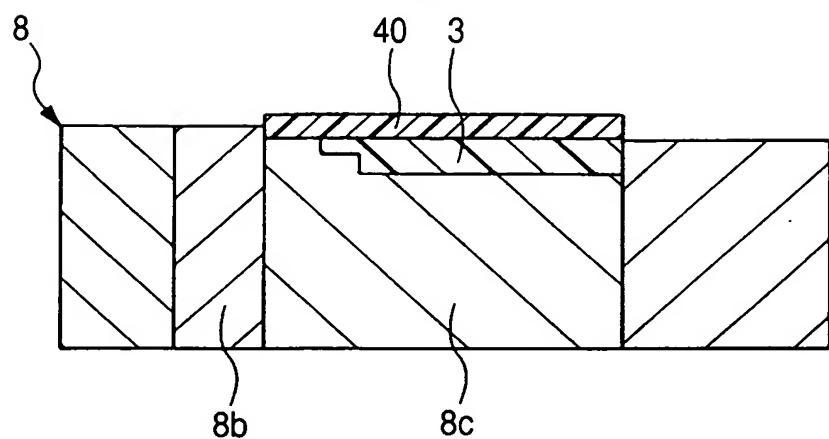


FIG. 8

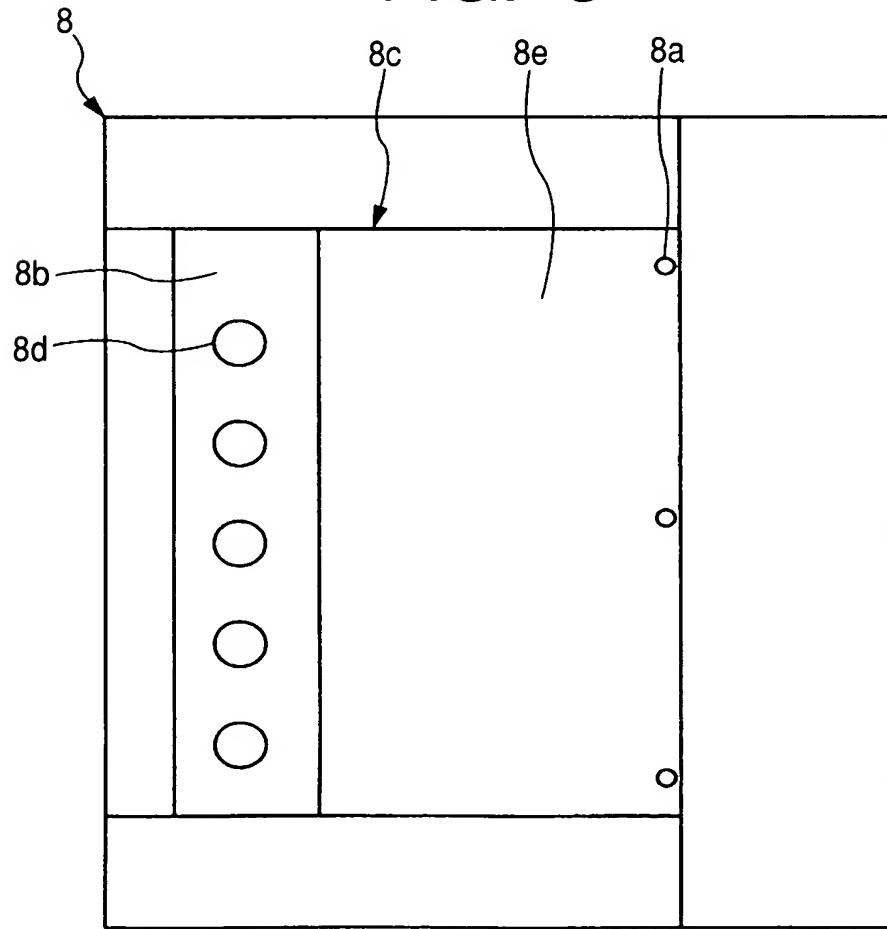


FIG. 9

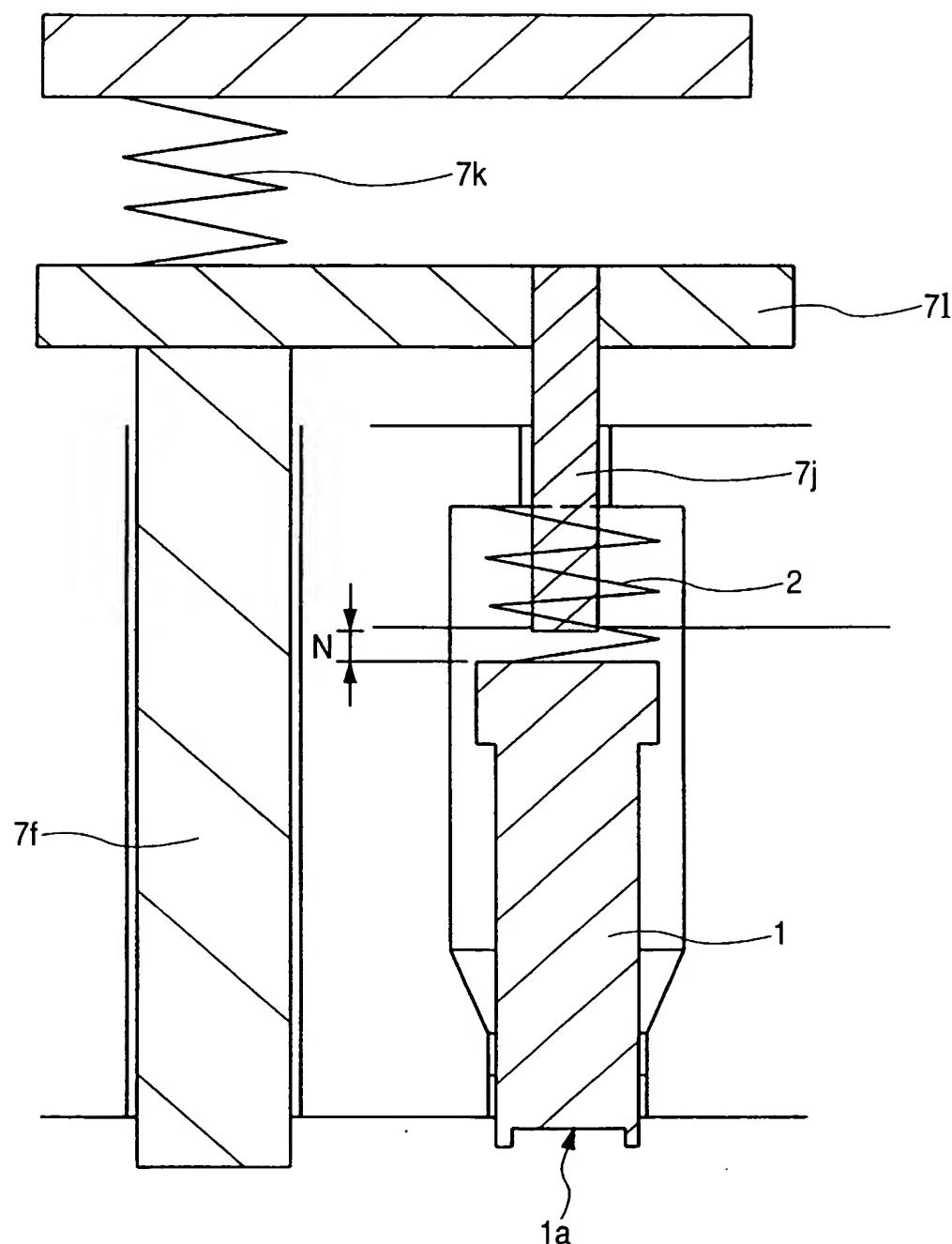


FIG. 10

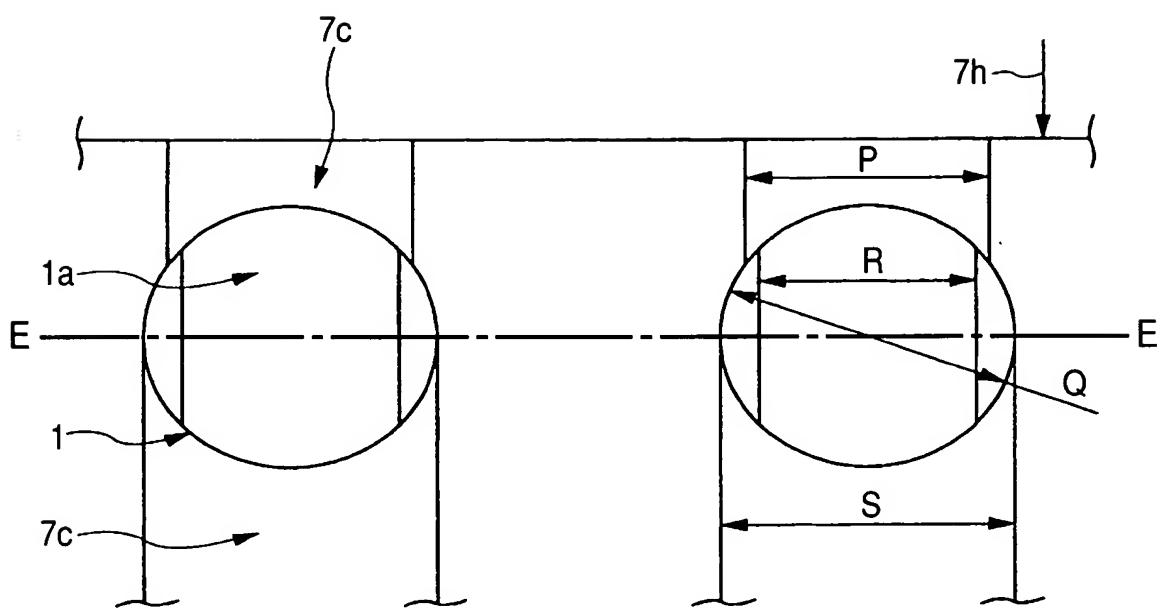


FIG. 11

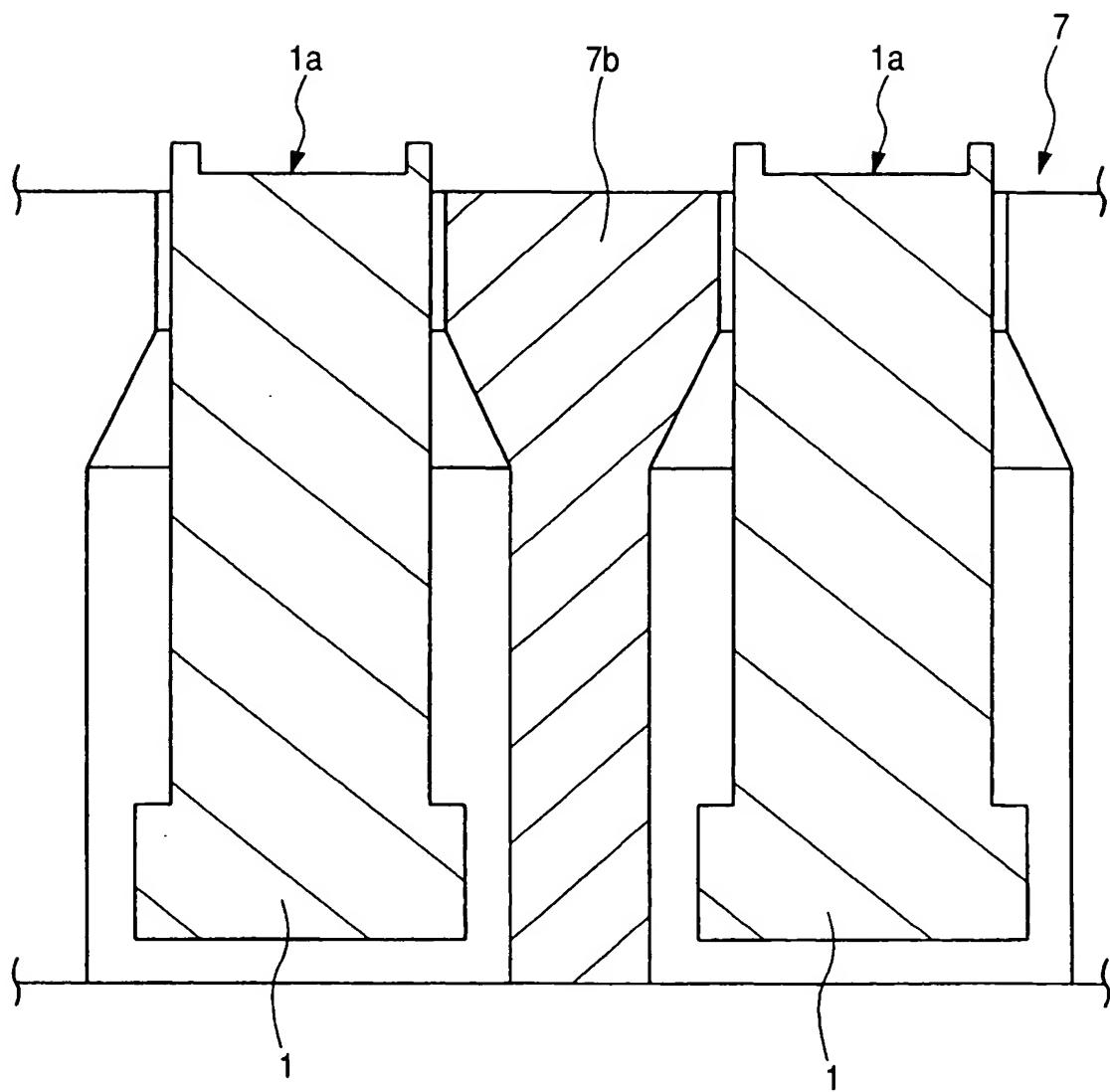


FIG. 12

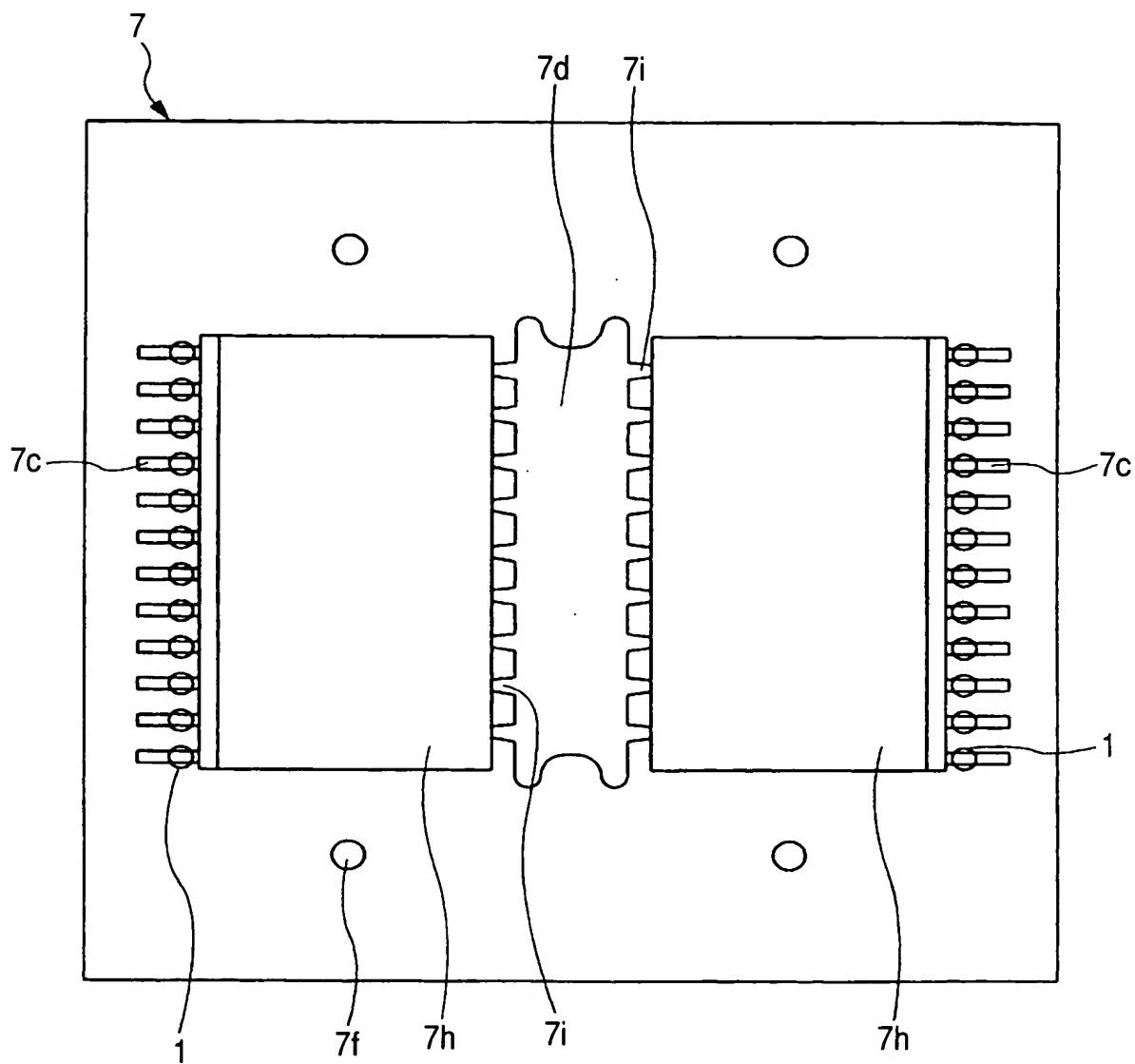


FIG. 13

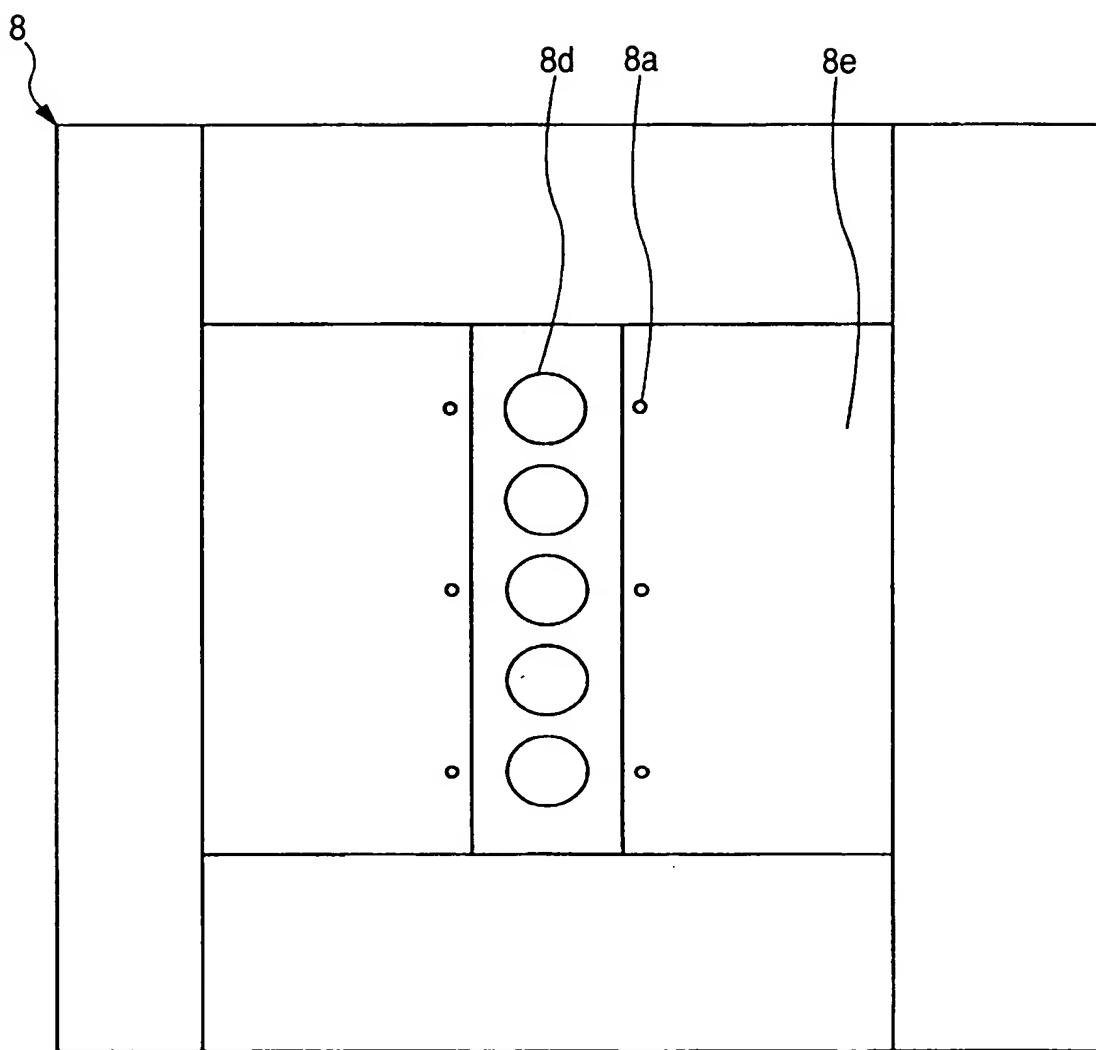
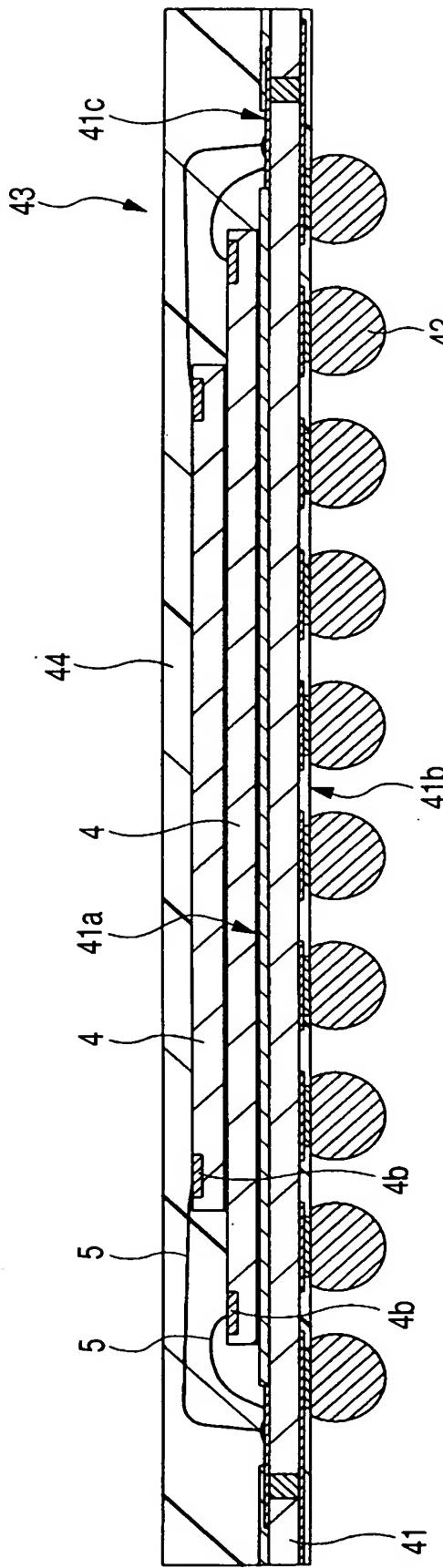
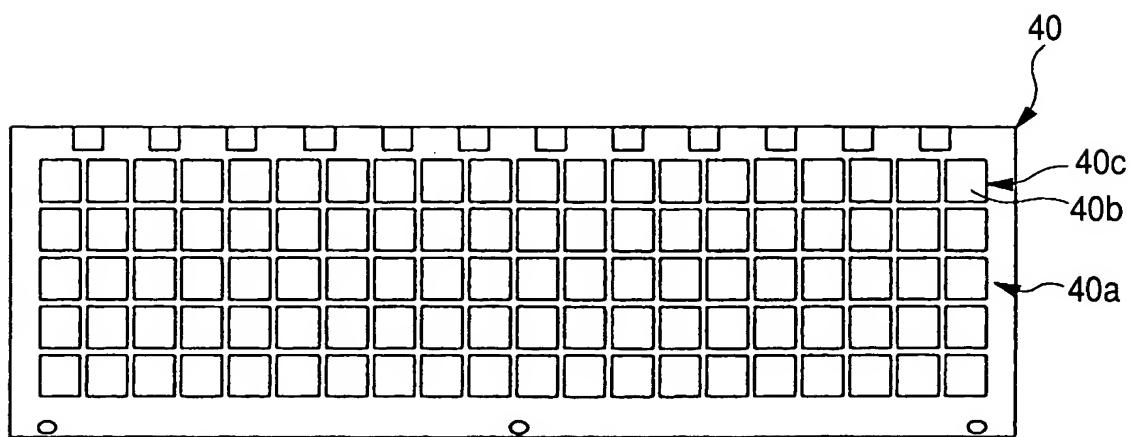


FIG. 14



4: SEMICONDUCTOR CHIP
 41: PRINTED WIRING BOARD (BOARD)
 43: CSP (SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE)

FIG. 15



40b : CHIP MOUNTING AREA
40c : DEVICE AREA (DEVICE FORMING AREA)

FIG. 16

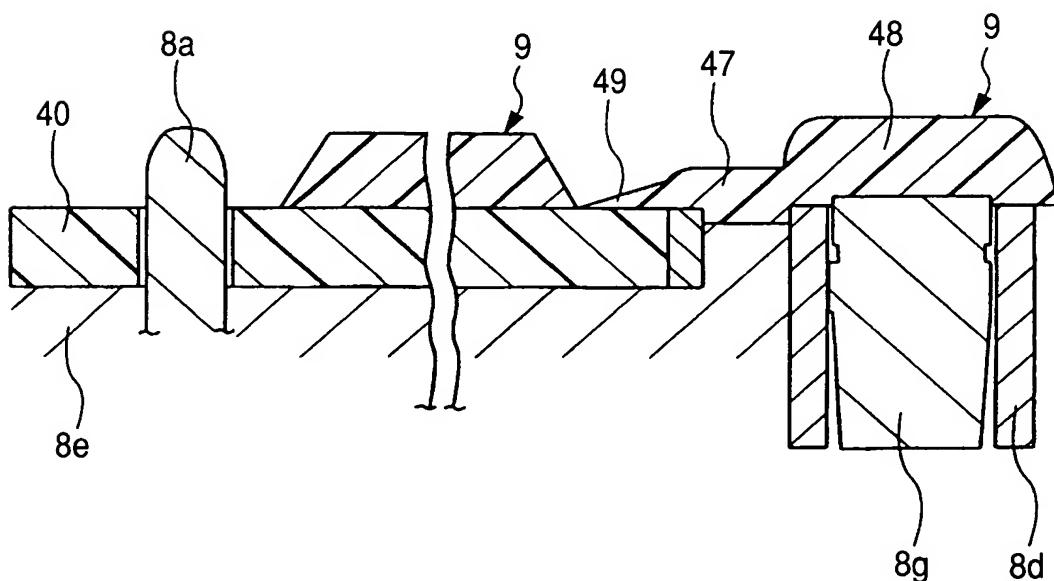


FIG. 17

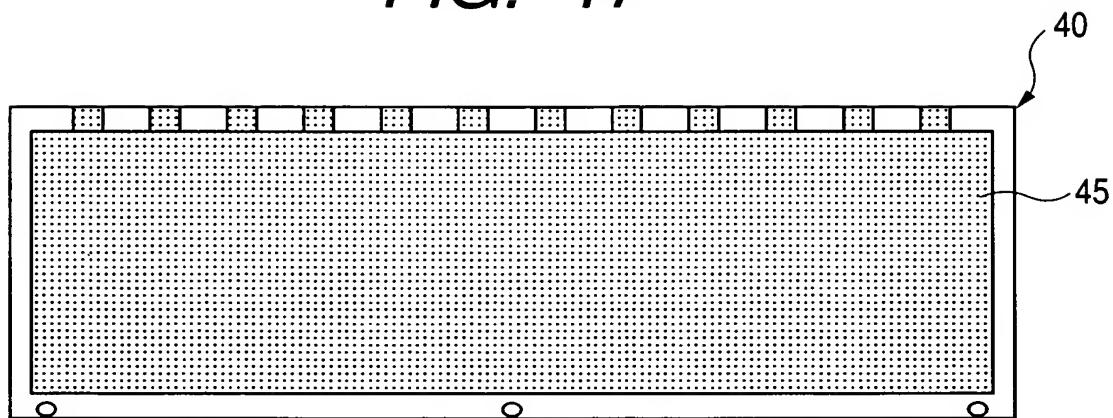


FIG. 18

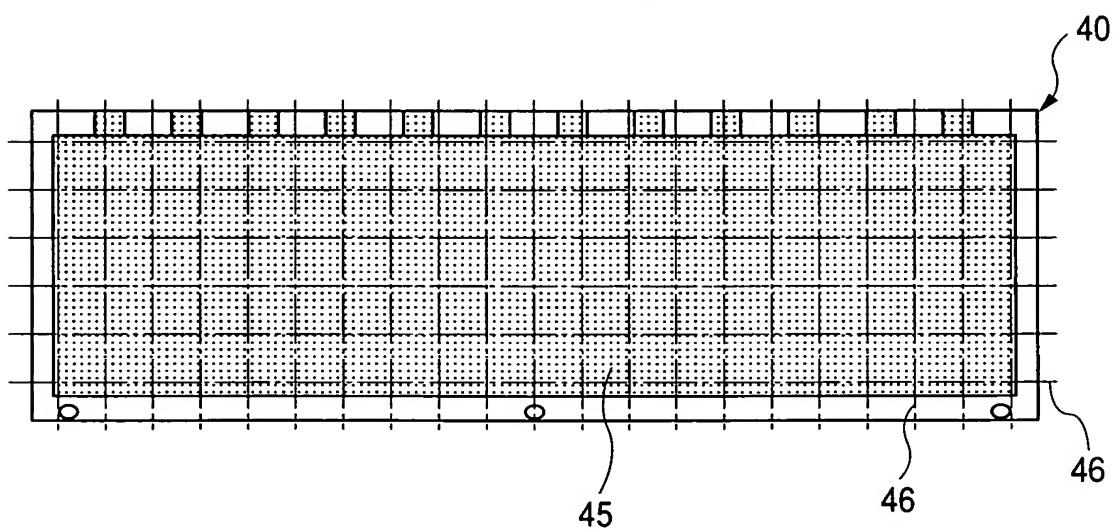


FIG. 19

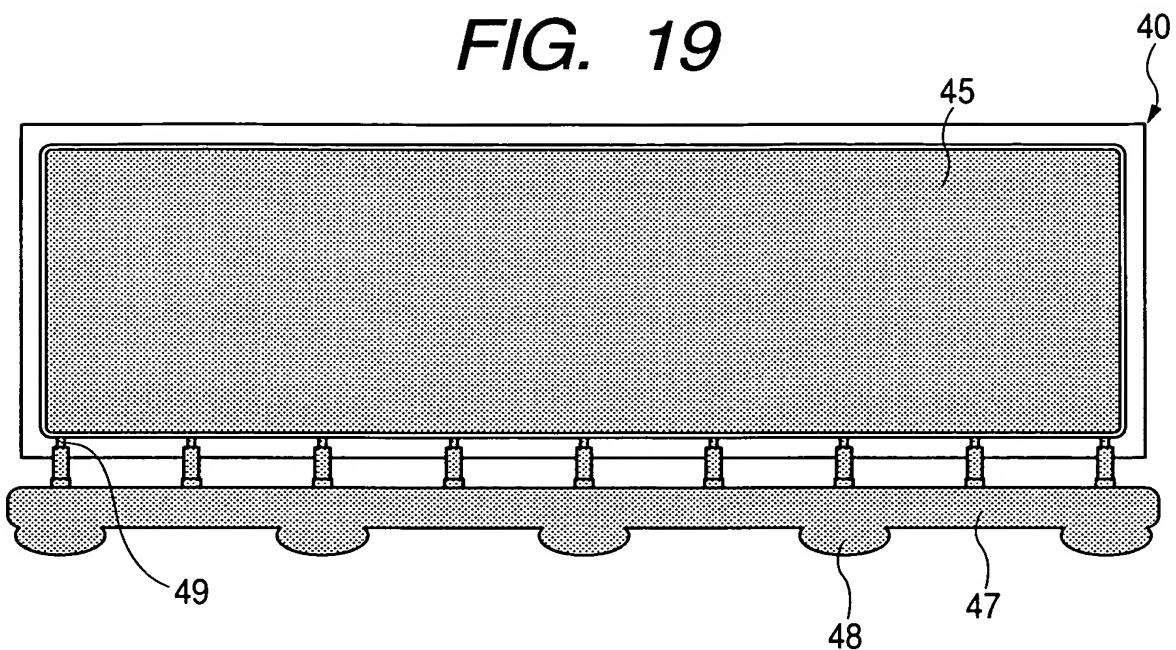


FIG. 20

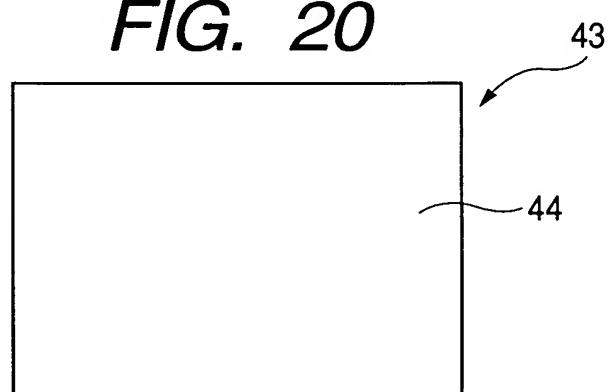


FIG. 21

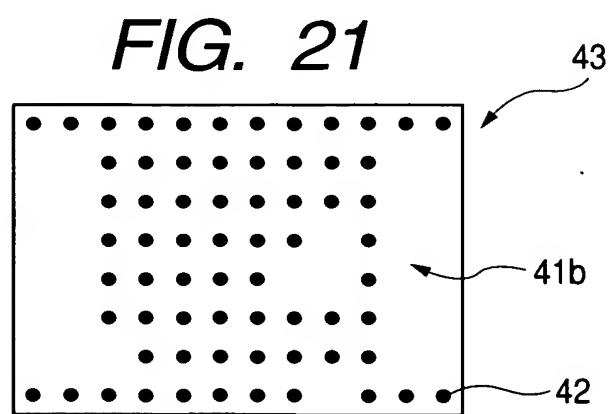
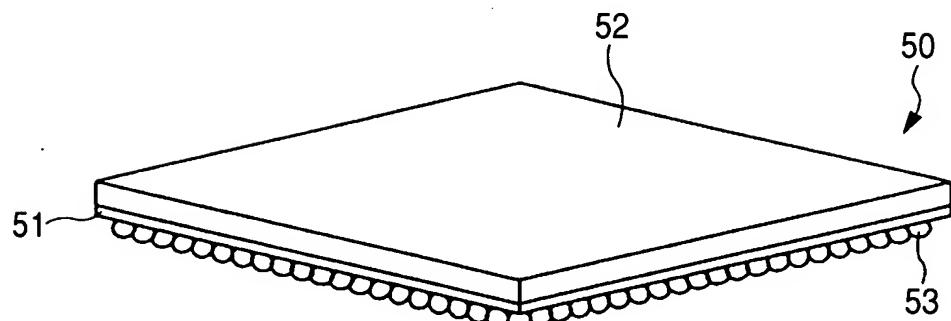
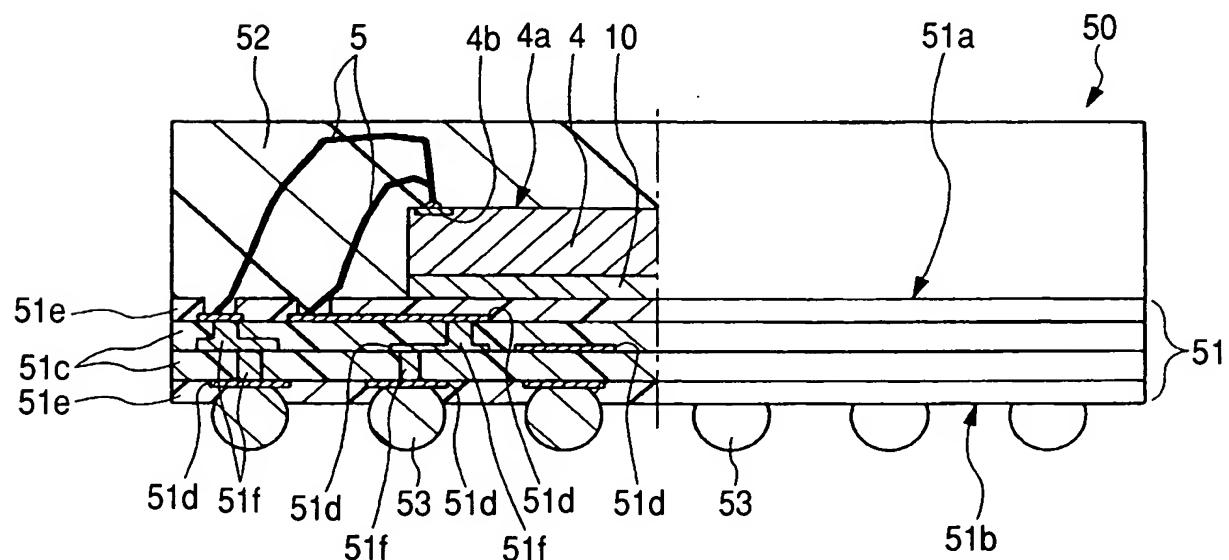


FIG. 22



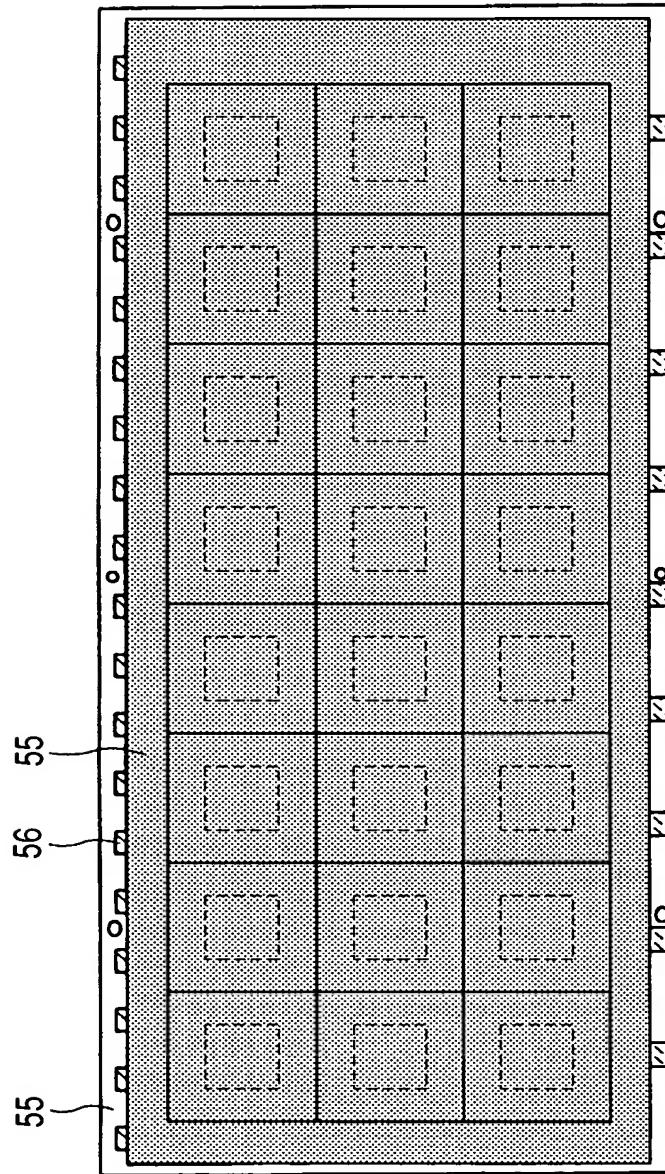
50 : CSP (SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE)
51 : MULTI-LAYERED PRINTED WIRING BOARD (BOARD)

FIG. 23



51c : CORE MEMBER

FIG. 24



54 : MULTI-CAVITY BOARD (BOARD)

FIG. 25

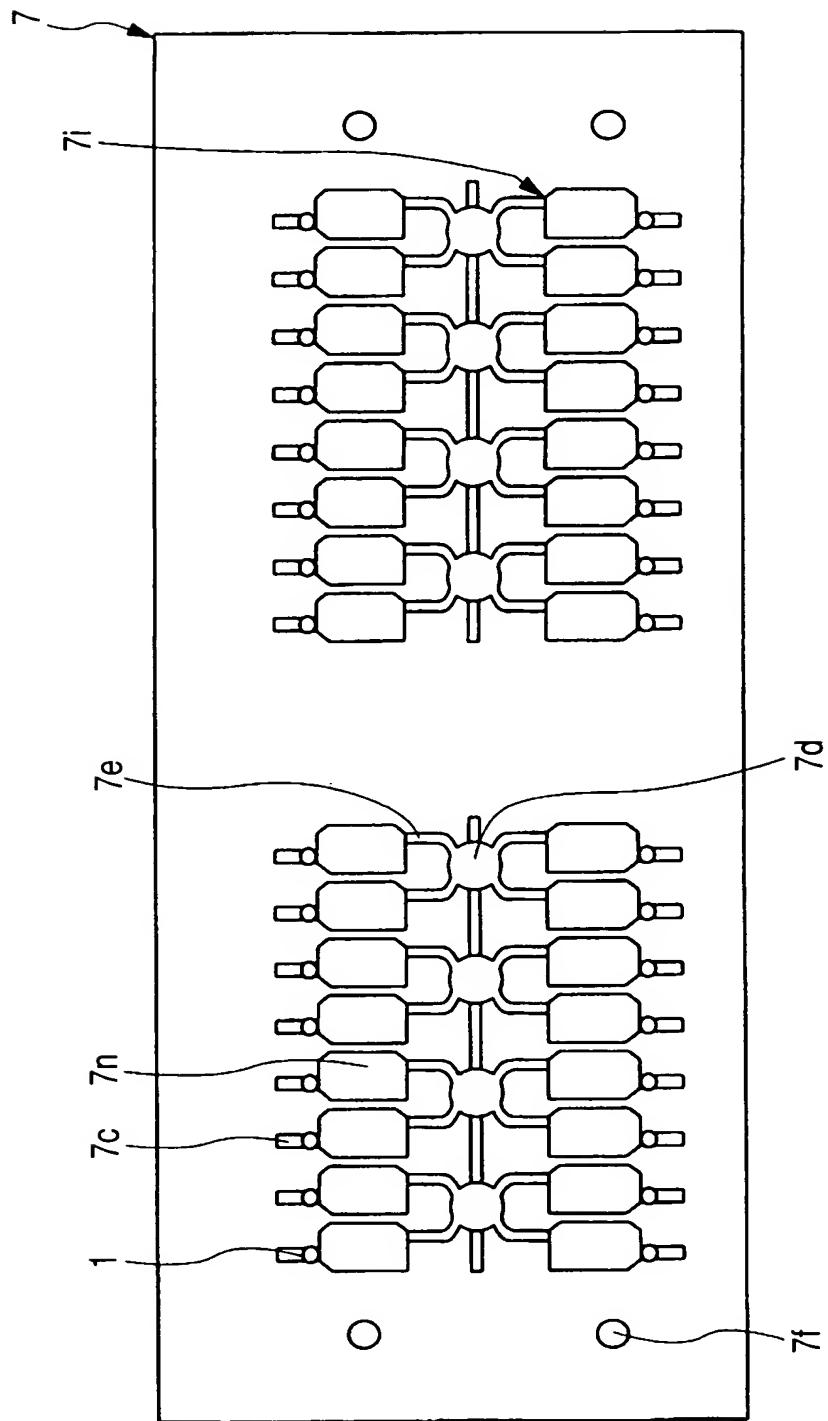
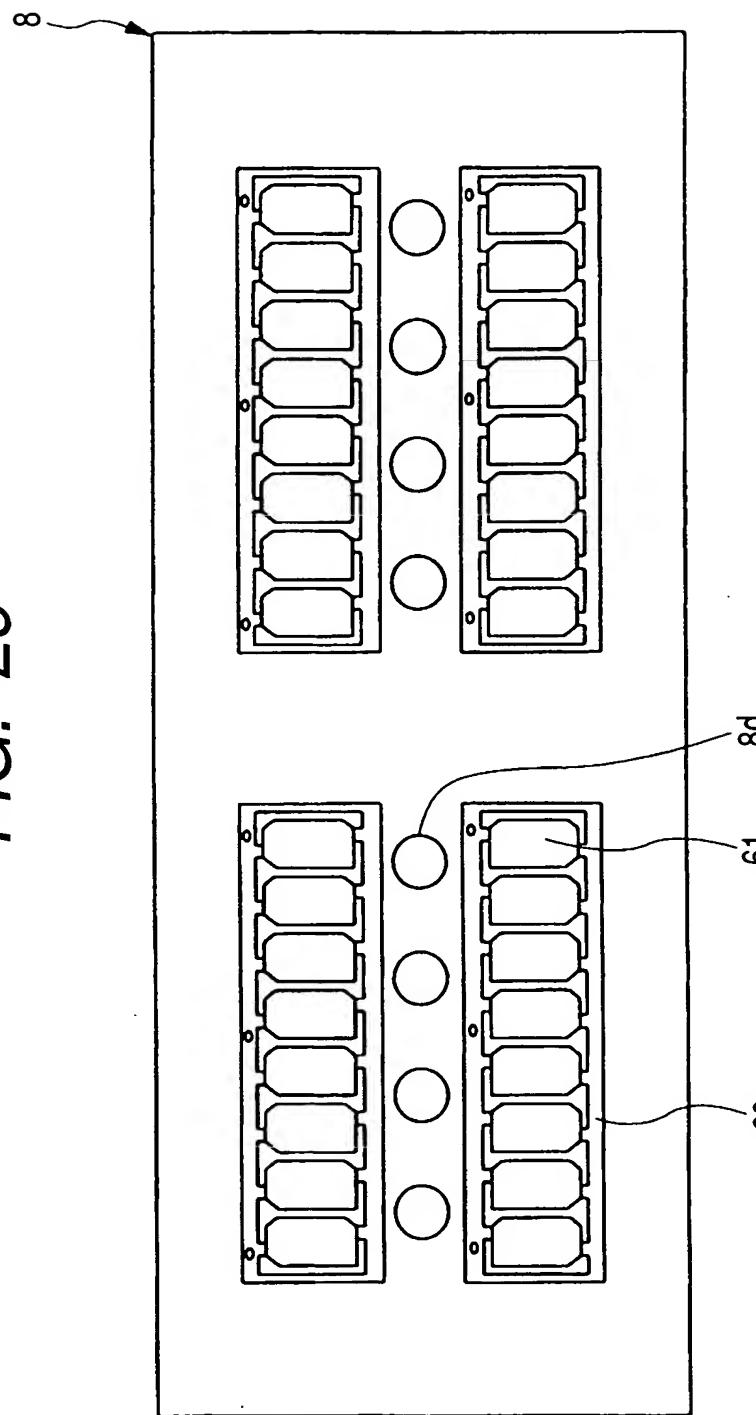


FIG. 26



60 : MULTI-CAVITY BOARD (BOARD)

FIG. 27

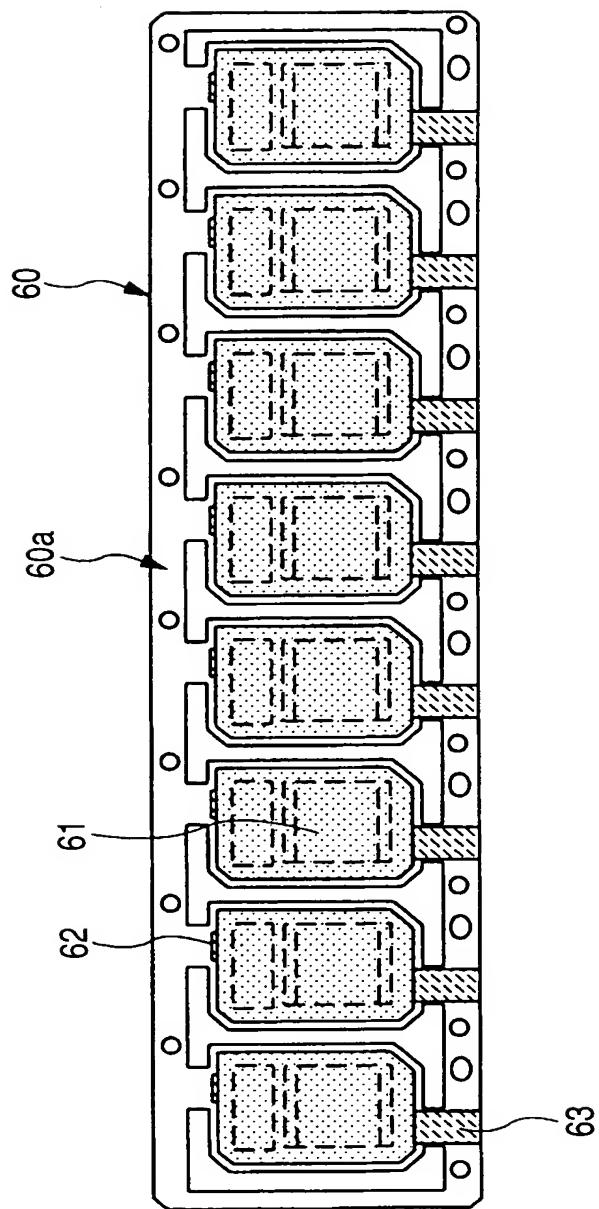
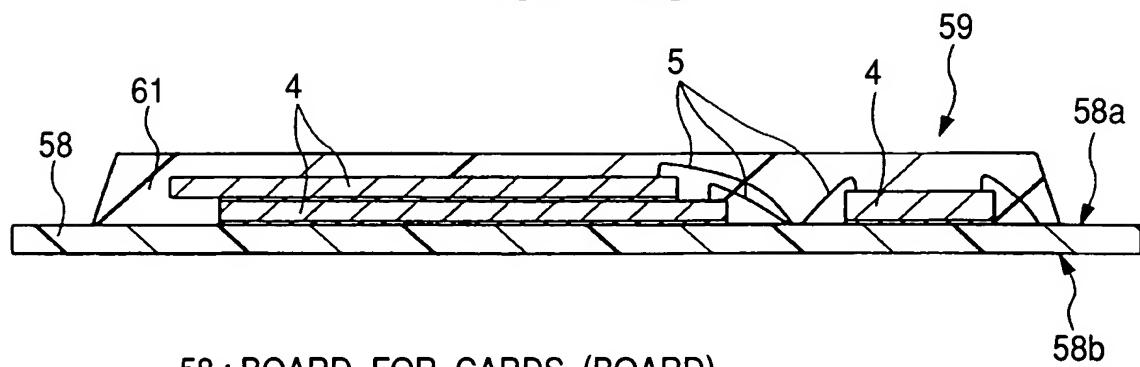


FIG. 28



58 : BOARD FOR CARDS (BOARD)

59 : CARD-TYPE PACKAGE

(SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE)

FIG. 29

